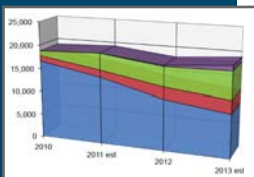
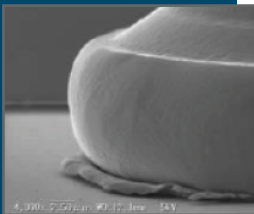


Advanced Packaging Update: Market and Technology Trends

Vol. 4-0713



This issue of the Advanced Packaging Update features special coverage of the market with a forecast for units of BGAs and CSPs by package construction. The BGA market is divided into plastic, tape, and ceramic structures. The CSP market is divided into laminate, flex circuit, and leadframe (QFN) substrates, as well as stacked die CSPs. Unit growth projections for BGA and CSP shipments plus package-on-package (PoP) are provided. Key applications and drivers for unit volume growth are highlighted. Trends in the conversion from gold wire to alternatives including silver, bare copper, and palladium-coated copper are also described and a breakdown of wire shipments by type is provided. A special section examines the growth in the smartphone market with an in-depth look at the role of Chinese handset manufacturers. An economic analysis examines macroeconomic trends and their impact on the semiconductor packaging and assembly industry.

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